

# BASIC BLADE & BEAM HEADER & SOCKET

(0.80 mm) .0315" PITCH • BTE/BSE SERIES



**BTE**  
Mates:  
BSE

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## SPECIFICATIONS

**Insulator Material:**  
Liquid Crystal Polymer  
**Contact Material:**  
Phosphor Bronze  
**Plating:**  
Au or Sn over 50  $\mu$ " (1.27  $\mu$ m) Ni  
**Current Rating:**  
2 A per pin  
(2 pins powered)  
**Operating Temp Range:**  
-55 °C to +125 °C  
**Voltage Rating:**  
225 VAC with 5 mm Stack Height  
**Max Cycles:**  
100

## PROCESSING

**Lead-Free Solderable:**  
Yes  
**SMT Lead Coplanarity:**  
(0.10 mm) .004" max (020-080)  
(0.15 mm) .006" max (100-120)\*  
\*(.004" stencil solution  
may be available; contact  
ipg@samtec.com)  
**Board Stacking:**  
For applications requiring more  
than two connectors per board  
or 80 positions or higher,  
contact ipg@samtec.com

## ALSO AVAILABLE

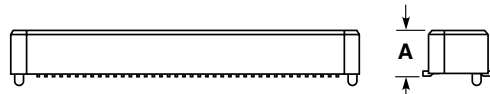
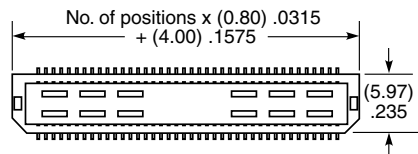
MOQ Required

30  $\mu$ " (0.76  $\mu$ m) Gold  
Edge Mount Capability  
Friction Lock option  
11 mm, 14 mm, 16.10 mm,  
19.10 mm, 22 mm, 25 mm  
and 30 mm Stack  
Height (Caution: Some  
automatic placement/  
inspection machines may  
have component height  
restrictions. Please consult  
machinery specifications.)



**Note:**  
Some lengths, styles and  
options are non-standard,  
non-returnable.

| BTE | NO. OF POSITIONS<br>PER ROW           | LEAD<br>STYLE                             | PLATING OPTION                                                                                                                                                                                                                                                                                                                                                                                                            | D | A | OTHER<br>OPTION                                                                                                                                                                                                                                                                                  |
|-----|---------------------------------------|-------------------------------------------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|---|---|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
|     | -020, -040, -060,<br>-080, -100, -120 | Specify<br>LEAD<br>STYLE<br>from<br>chart | -F<br>= Gold Flash on contact,<br>Matte Tin on tail<br><br>-L<br>= 10 $\mu$ " (0.25 $\mu$ m)<br>Gold on contact,<br>Matte Tin on tail<br><br>-C*<br>= Electro-Polished Selective<br>50 $\mu$ " (1.27 $\mu$ m) min<br>Au over 150 $\mu$ " (3.81 $\mu$ m)<br>Ni on Signal Pins in contact<br>area, Matte Tin over<br>50 $\mu$ " (1.27 $\mu$ m) min<br>Ni on all solder tails<br>(*-C Plating passes<br>10 year MFG testing) |   |   | -K<br>= (7.00 mm)<br>.275" DIA<br>Polyimide Film<br>Pick & Place Pad<br><br>-TR<br>= Tape & Reel<br>(80 positions<br>maximum)<br><br>-FR<br>= Full Reel<br>Tape & Reel<br>(must order<br>maximum<br>quantity per<br>reel; contact<br>Samtec for<br>quantity breaks)<br>(80 positions<br>maximum) |



| LEAD<br>STYLE | A           |
|---------------|-------------|
| -01           | (4.27) .168 |
| -02           | (7.21) .284 |

## MATED HEIGHT

| LEAD STYLE | MATED HEIGHT*    |
|------------|------------------|
| -01        | (5.00 mm) .1971" |
| -02        | (8.00 mm) .315"  |

\*Processing conditions  
will affect mated height.

| BSE | NO. OF POSITIONS<br>PER ROW           | 01 | PLATING OPTION                                                                                                                                                                                                                                                                                                                                                                                                            | D | A | OTHER<br>OPTION                                                                                                                                                                                                      |
|-----|---------------------------------------|----|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|---|---|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
|     | -020, -040, -060,<br>-080, -100, -120 |    | -F<br>= Gold Flash on contact,<br>Matte Tin on tail<br><br>-L<br>= 10 $\mu$ " (0.25 $\mu$ m)<br>Gold on contact,<br>Matte Tin on tail<br><br>-C*<br>= Electro-Polished Selective<br>50 $\mu$ " (1.27 $\mu$ m) min<br>Au over 150 $\mu$ " (3.81 $\mu$ m)<br>Ni on Signal Pins in contact<br>area, Matte Tin over<br>50 $\mu$ " (1.27 $\mu$ m) min<br>Ni on all solder tails<br>(*-C Plating passes<br>10 year MFG testing) |   |   | -TR<br>= Tape & Reel<br>(80 positions<br>maximum)<br><br>-FR<br>= Full Reel<br>Tape & Reel<br>(must order<br>maximum<br>quantity per<br>reel; contact<br>Samtec for<br>quantity breaks)<br>(80 positions<br>maximum) |

